#### D3555, JULY 1990

Maximum Output Skew of 1 ns	D OR N PACKAGE (TOP VIEW)			
Maximum Pulse Skew of 1 ns	(			
<ul> <li>Center-Pin V<sub>CC</sub> and GND Configurations to Minimize High-Speed Switching Noise</li> </ul>	Q3[ 1 Q4[] 2 GND[ 3	16] Q2 15] Q1 14] CLR		
<ul> <li>Package Options Include Plastic "Small</li> </ul>	GND 4	13 VCC		
Outline" Packages, and Standard Plastic	GND 🛛 5	12 VCC		
300-mil DIPs	Q5[] 6	11 ] CLK		
	Q6[ <b>[</b> 7	10 ] PRE		
description	Q7[ 8	9 Q8		

The SN74AS304 contains eight flip-flops designed to have low skew between outputs. The eight outputs (in-phase with CLK) toggle on successive CLK pulses. PRE and CLR pins are provided to set the Q outputs high or low independent of the CLK input.

The SN74AS304 has output and pulse skew parameters  $t_{sk(o)}$  and  $t_{sk(p)}$  to ensure performances as a clock driver when a divide-by-two function is required.

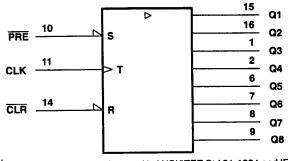
The SN74AS304 is characterized for operation from 0°C to 70°C.

	INPUT	S	OUTPUTS
CLR	PRE	CLK	Q1–Q8
L	Н	х	L
Н	L	х	н
L	L	х	Lt
н	н	t	<u>a</u> 0
Н	н	L	Q <sub>0</sub>

FUNCTION TABLE

<sup>†</sup> This configuration will not persist when  $\overline{\text{PRE}}$  or  $\overline{\text{CLR}}$  returns to its inactive (high) level.

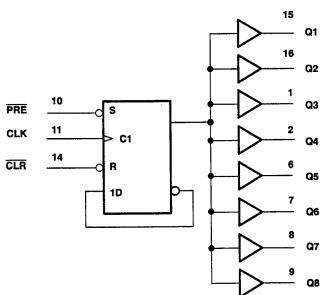
### logic symbol<sup>‡</sup>



<sup>‡</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



### logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>
Input voltage, V <sub>I</sub>
Operating free-air temperature range
Storage temperature range – 65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	<b>5</b> .5	V
VIH	High-level input voltage	2			- V
VIL	Low-level input voltage			0.8	V
ЮН	High-level output current			- 24	mA
IOL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C



### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST C	MIN TYP <sup>†</sup>	MAX	UNIT	
VIK	V <sub>CC</sub> = 4.5 V,	lj = 18 mA		- 1.2	V
	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = 2 mA	Vcc <sup>-2</sup>		v
<sup>V</sup> ОН	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = - 24 mA	2 2.8		
VOL	V <sub>CC</sub> = 4.5 V,	IOL = 48 mA	0.3	0.5	V
4	V <sub>CC</sub> = 5.5 V,	V <sub>1</sub> = 7 V		0.1	mA
Iн	V <sub>CC</sub> = 5.5 V,	VI = 2.7 V		20	μA
lμ	V <sub>CC</sub> = 5.5 V,	V <sub>1</sub> = 0.4 V		- 0.5	mA
10 <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	- 50	- 150	mA
lcc	V <sub>CC</sub> = 5.5 V,	See Note 1	45	75	mA

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. <sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS. NOTE 1: I<sub>CC</sub> is measured with CLK and PRE grounded, then with CLK and CLR grounded.

#### timing requirements

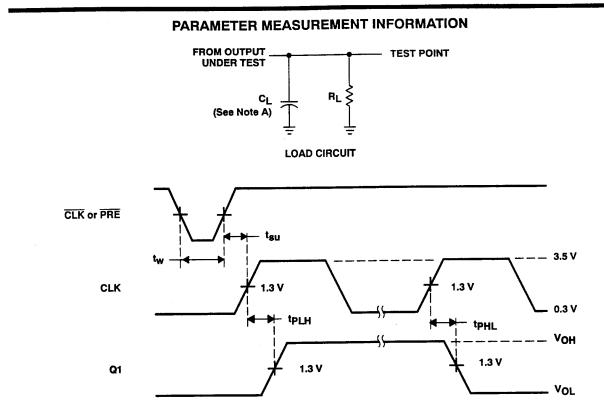
PARAMETER			MIN	NOM	MAX	UNIT
fclock	clock frequency		0	80		MHz
		CLK high	4			
tw Pulse duration	CLK low	6			ns	
	CLR or PRE low	5				
t <sub>su</sub>	Setup time before CLK↑	CLR or PRE inactive	6			ns

# switching characteristics over recommended operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP†	мах	UNIT
f <sub>max</sub> §				80			MHz
tPLH				26	6	9	
tPHL	CLK	Q	$R_L = 500 \Omega$ , $C_L = 50 pF$	2	6	9	ns
tPLH		_		3	7	12	
<sup>t</sup> PHL	PRE or CLR	Q	$R_L = 500 \Omega$ , $C_L = 50 pF$	3	7	12	ns
tsk(o)	CLK	Q	$R_{L} = 500 \Omega$ , $C_{L} = 10 pF to 30 pF$			1	ns
		Q1, Q8				1	
<sup>t</sup> sk(p)	CLK	Q2 to Q7	$R_L = 500 \Omega$ , $C_L = 10 \text{ pF to 30 pF}$			1.5	ns
tr	1	•				4.5	ns
tr						3.5	ns

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. §  $f_{max}$  minimum values are at C<sub>L</sub> = 0 to 30 pF.



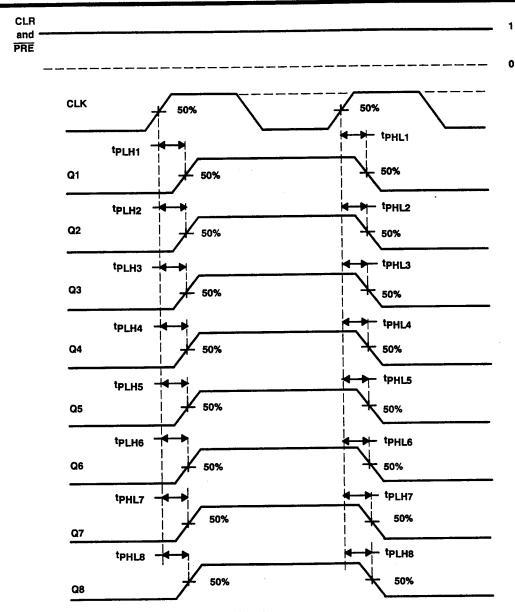


NOTES: A. CL includes probe and jig capacitance.

B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, t<sub>f</sub> = 2.5 ns, t<sub>f</sub> = 2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms





NOTES: A. t<sub>sk(o)</sub>, CLK to Q, is calculated as the greater of the following:
1. The difference between the fastest and slowest of tp<sub>LHn</sub> (n = 1, 2, 3 . . ., 8).
2. The difference between the fastest and slowest of tp<sub>HLn</sub> (n = 1, 2, 3 . . ., 8).
B. t<sub>sk(p)</sub> is defined at the greater of | tp<sub>LHn</sub> - tp<sub>HLn</sub> | (n = 1, 2, 3, . . ., 8).

Figure 2. Waveforms for Calculation of tsk(o)



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AS304D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN74AS304DR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
SN74AS304N	OBSOLETE	PDIP	Ν	16	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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